

4V Drive Nch+Pch MOSFET

SP8M10FRA

●Structure

Silicon N-channel / P-channel MOSFET

●Features

- 1) Low on-resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (SOP8).

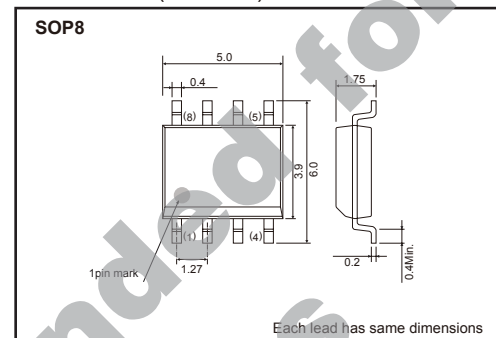
●Application

Power switching, DC / DC converter.

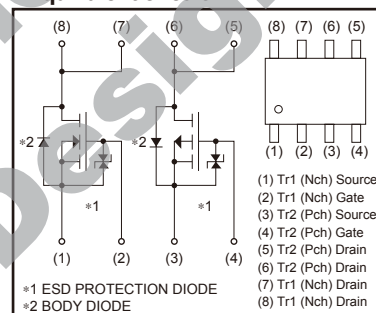
●Packaging specifications

| Type | Package | Taping |
|-----------|----------------|--------|
| | Code | TB |
| | Quantity (pcs) | 2500 |
| SP8M10FRA | | ○ |

●Dimensions (Unit : mm)



●Equivalent circuit



*A protection diode is included between the gate and the source terminals to protect the diode against static electricity when the product is in use. Use the protection circuit when the fixed voltages are exceeded.

●Absolute maximum ratings (Ta=25°C)

| Parameter | Symbol | Limits | | Unit | |
|-----------------------------|-------------------|--------------------|----------|------|---|
| | | Nchannel | Pchannel | | |
| Drain-source voltage | V _{DSS} | 30 | -30 | V | |
| Gate-source voltage | V _{GSS} | ±20 | ±20 | V | |
| Drain current | Continuous | I _D | ±7.0 | ±4.5 | A |
| | Pulsed | I _{DP} *1 | ±28 | ±18 | A |
| Source current (Body diode) | Continuous | I _S | 1.6 | -1.6 | A |
| | Pulsed | I _{SP} *1 | 28 | -18 | A |
| Total power dissipation | P _D *2 | 2 | | W | |
| Channel temperature | T _{ch} | 150 | | °C | |
| Storage temperature | T _{stg} | -55 to +150 | | °C | |

*1 Pw≤10μs, Duty cycle≤1%

*2 MOUNTED ON A CERAMIC BOARD.

●Thermal resistance

| Parameter | Symbol | Limits | Unit |
|--------------------|--------------------------|--------|--------|
| Channel to ambient | R _{th (ch-a)} * | 62.5 | °C / W |

*MOUNTED ON A CERAMIC BOARD.

Transistors

N-ch

●Electrical characteristics (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|---|-----------------------|------|------|------|------|---|
| Gate-source leakage | I _{GSS} | – | – | ±10 | μA | V _{GS} =±20V, V _{DS} =0V |
| Drain-source breakdown voltage | V _{(BR) DSS} | 30 | – | – | V | I _D =1mA, V _{GS} =0V |
| Zero gate voltage drain current | I _{DSS} | – | – | 1 | μA | V _{DS} =30V, V _{GS} =0V |
| Gate threshold voltage | V _{GS(th)} | 1.0 | – | 2.5 | V | V _{DS} =10V, I _D =1mA |
| Static drain-source on-state resistance | R _{DS(on)} * | – | 17 | 25 | mΩ | I _D =7.0A, V _{GS} =10V |
| | | – | 23 | 35 | | I _D =7.0A, V _{GS} =4.5V |
| | | – | 25 | 37 | | I _D =7.0A, V _{GS} =4V |
| Forward transfer admittance | Y _{fs} * | 5.0 | – | – | S | I _D =7.0A, V _{DS} =10V |
| Input capacitance | C _{iss} | – | 600 | – | pF | V _{DS} =10V |
| Output capacitance | C _{oss} | – | 200 | – | pF | V _{GS} =0V |
| Reverse transfer capacitance | C _{rss} | – | 120 | – | pF | f=1MHz |
| Turn-on delay time | t _{d(on)} * | – | 8 | – | ns | I _D =3.5A, V _{DD} =15V |
| Rise time | t _r * | – | 10 | – | ns | V _{GS} =10V |
| Turn-off delay time | t _{d(off)} * | – | 37 | – | ns | R _L =4.29Ω |
| Fall time | t _f * | – | 11 | – | ns | R _G =10Ω |
| Total gate charge | Q _g * | – | 8.4 | – | nC | V _{DD} =15V |
| Gate-source charge | Q _{gs} * | – | 1.9 | – | nC | V _{GS} =5V |
| Gate-drain charge | Q _{gd} * | – | 3.3 | – | nC | I _D =7.0A |

*Pulsed

●Body diode characteristics (Source-Drain) (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-----------------|-------------------|------|------|------|------|---|
| Forward voltage | V _{SD} * | – | – | 1.2 | V | I _S =6.4A, V _{GS} =0V |

*Pulsed

Transistors

P-ch

●Electrical characteristics (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|---|-----------------------|------|------|------|------|---|
| Gate-source leakage | I _{GSS} | – | – | ±10 | μA | V _{GS} = ±20V, V _{DS} =0V |
| Drain-source breakdown voltage | V _{(BR) DSS} | –30 | – | – | V | I _D = –1mA, V _{GS} =0V |
| Zero gate voltage drain current | I _{DSS} | – | – | –1 | μA | V _{DS} = –30V, V _{GS} =0V |
| Gate threshold voltage | V _{GS(th)} | –1.0 | – | –2.5 | V | V _{DS} = –10V, I _D = –1mA |
| Static drain-source on-state resistance | R _{DS(on)} * | – | 40 | 56 | mΩ | I _D = –4.5A, V _{GS} = –10V |
| | | – | 57 | 80 | | I _D = –2.5A, V _{GS} = –4.5V |
| | | – | 65 | 90 | | I _D = –2.5A, V _{GS} = –4.0V |
| Forward transfer admittance | Y _{fs} * | 3.5 | – | – | S | I _D = –2.5A, V _{DS} = –10V |
| Input capacitance | C _{iss} | – | 850 | – | pF | V _{DS} = –10V |
| Output capacitance | C _{oss} | – | 190 | – | pF | V _{GS} =0V |
| Reverse transfer capacitance | C _{rss} | – | 120 | – | pF | f=1MHz |
| Turn-on delay time | t _{d(on)} * | – | 10 | – | ns | I _D = –2.5A, V _{DD} = –15V |
| Rise time | t _r * | – | 25 | – | ns | V _{GS} = –10V |
| Turn-off delay time | t _{d(off)} * | – | 60 | – | ns | R _L =6.0Ω |
| Fall time | t _f * | – | 25 | – | ns | R _G =10Ω |
| Total gate charge | Q _g * | – | 8.5 | – | nC | V _{DD} = –15V |
| Gate-source charge | Q _{gs} * | – | 2.5 | – | nC | V _{GS} = –5V |
| Gate-drain charge | Q _{gd} * | – | 3.0 | – | nC | I _D = –4.5A |

*Pulsed

●Body diode characteristics (Source-Drain) (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-----------------|-----------------|------|------|------|------|---|
| Forward voltage | V _{SD} | – | – | –1.2 | V | I _S = –1.6A, V _{GS} =0V |

Transistors

N-ch

●Electrical characteristic curves

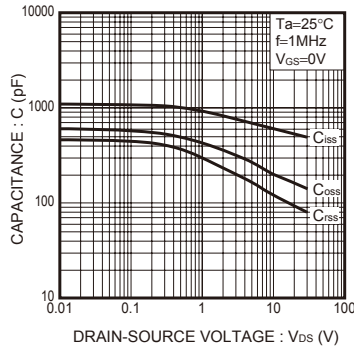


Fig.1 Typical Capacitance vs. Drain-Source Voltage

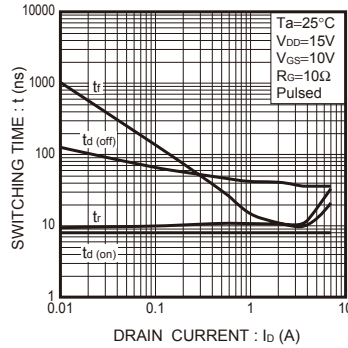


Fig.2 Switching Characteristics

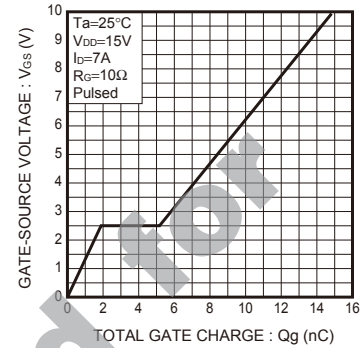


Fig.3 Dynamic Input Characteristics

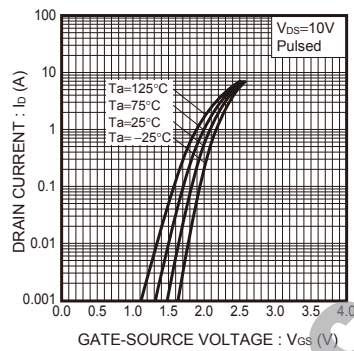


Fig.4 Typical Transfer Characteristics

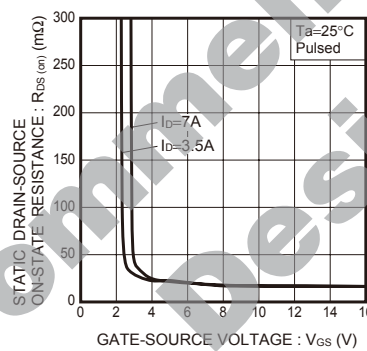


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

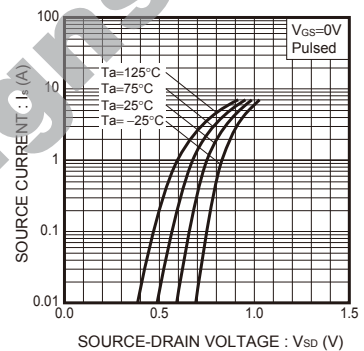


Fig.6 Source Current vs. Source-Drain Voltage

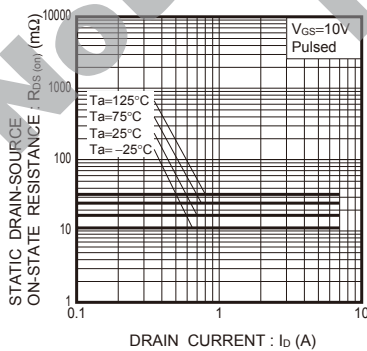


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

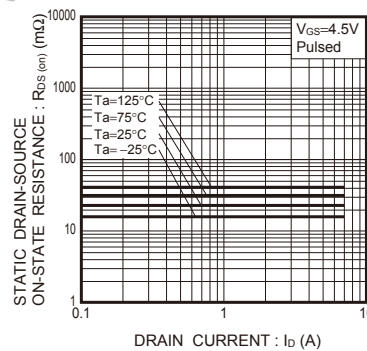


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

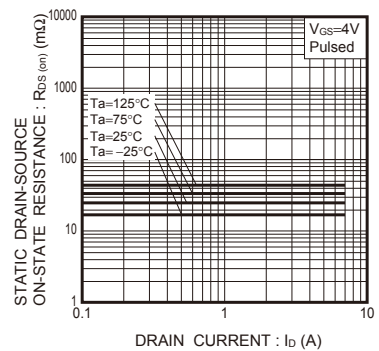


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

Transistors

P-ch

●Electrical characteristic curves

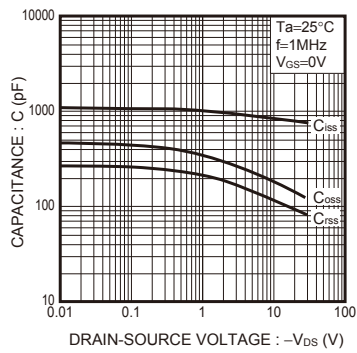


Fig.1 Typical Capacitance vs. Drain-Source Voltage

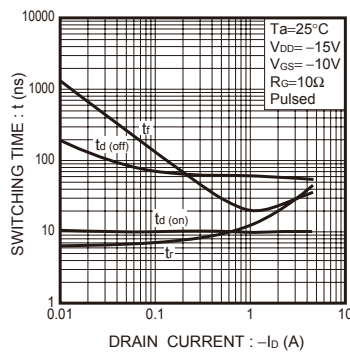


Fig.2 Switching Characteristics

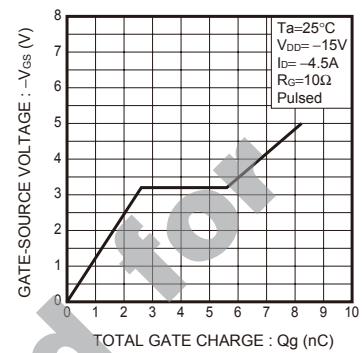


Fig.3 Dynamic Input Characteristics

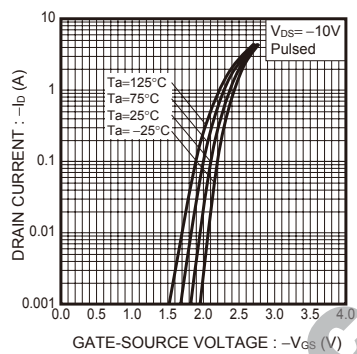


Fig.4 Typical Transfer Characteristics

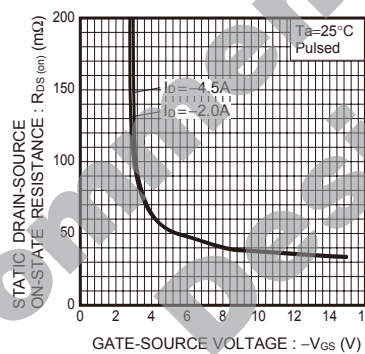


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

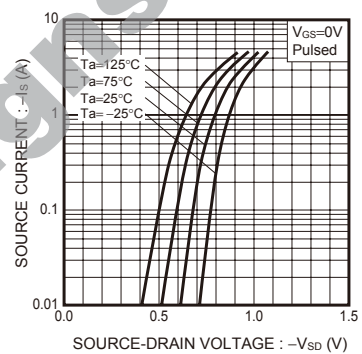


Fig.6 Source Current vs. Source-Drain Voltage

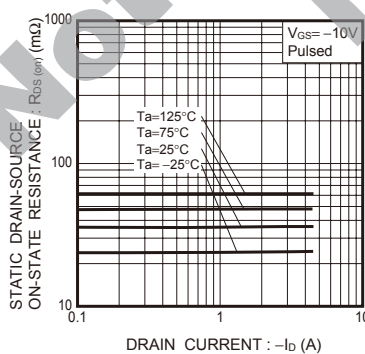


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

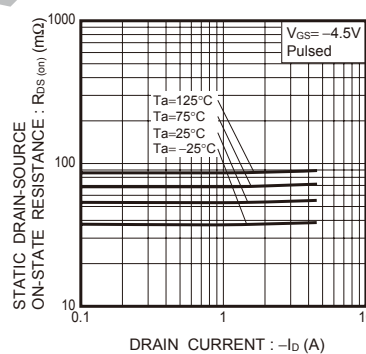


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

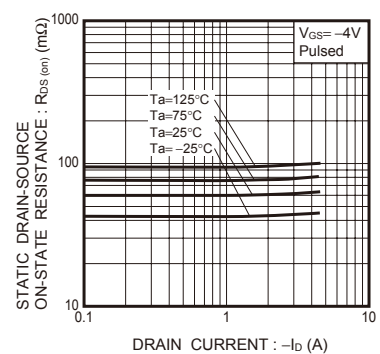


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

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| JAPAN | USA | EU | CHINA |
|-----------|-----------|------------|-----------|
| CLASS III | CLASS III | CLASS II b | CLASS III |
| CLASS IV | | CLASS III | |

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
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 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
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4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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